Laird TECHNOLOGIES®

Innovative **Technology** for a **Connected** World

SNC70-RXP Form-In-Place



* does not represent actual color

SNC70-RXP Form-In-Place

A rapid cure, nickel/graphite-filled silicone elastomer Form-In-Place gasket material.

Laird Technologies introduces another product in the EMI Sentry family. These Form-In-Place pastes are extremely fast curing with reliable shielding effectiveness and strength.

Laird Technologies' Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for base stations, PDAs, PC cards, radios, mobile phones, as well as many other cast or plastic enclosures and packaged electronic assemblies.

TYPICAL VALUES

	TEST METHOD	UNITS	SNC70-RXP
Elastomer			Silicone
Filler			Nickel/Graphite
ELECTRICAL PROPERTIES			
Volume Resistivity		ohm-cm	0.030
Shielding Effectiveness	MIL-DTL-83528C		
200 MHz to 10 GHz	Para. 4.5.12	dB	>100
PHYSICAL PROPERTIES			
Hardness	ASTM D2240	Shore A	70
Tensile Strength	ASTM D412	psi	180
Tensile Elongation	ASTM D412	%	50
Density (cured)	ASTM D792	g/cm^3	2.5
Density (uncured)	LT-FIP-CLE-09	g/cm^3	2.1
Compression Set	ASTM D395	%	15
Adhesion Strength (Al)	LT-FIP-CLE-03	N/cm^2	150
Compression-Deflection (a)	LT-FIP-CLE-07		
at 20% compression		lb/in	1.5
at 40% compression		lb/in	7.9
Temperature Range		°C	-50°C to 125°C
UL rating	UL-94		V0
CURING REQUIREMENTS			
Cure Conditions	15°C to 40°C, 50% relative humidity		
At 22°C and 50% RH	LT-FIP-CLE-14		
Time before handling			1 hour
Full Cure			24 hours

(a) Compression-deflection bead size 0.62 mm (H) x 0.70 mm (W)

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global solutions: local support™

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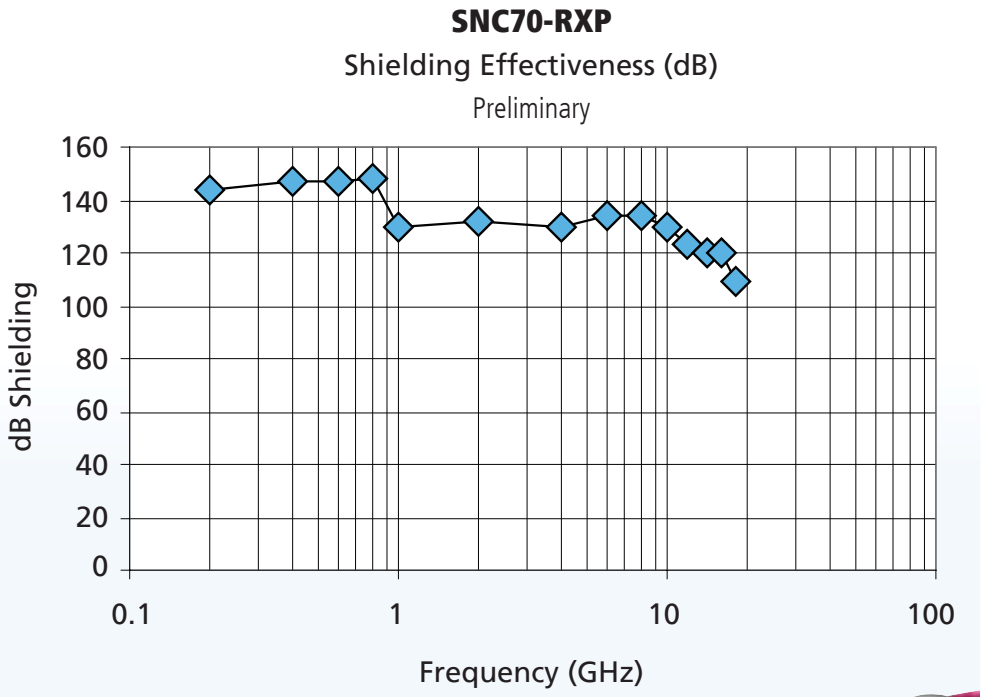
A rapid cure, nickel/graphite-filled silicone elastomer Form-In-Place gasket material.

SNC70-RXP is one of the new products in the EMI Sentry line. This paste has dynamic shielding effectiveness, strength for environmental protection, and is a room temperature-cured paste. Products in the EMI Sentry line all have superior adhesion strength, strong reliability in low compression sets, as well as heat and humidity resistance.





EMI SENTRY™

EMI-DS-FIP-SNC70-RXP 0709

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